

BCM857BS

PNP matched double transistor; $\Delta h_{FE} = 10\%$

Rev. 01 — 14 September 2004

Product data sheet

1. Product profile

1.1 General description

PNP matched double transistor in SOT363 (SC-88) SMD plastic package. Matched version of BC857BS. The transistors are fully isolated internally. NPN equivalent: BCM847BS.

1.2 Features

- Current gain matching
- Base-emitter voltage matching.

1.3 Applications

- Current mirror
- Differential amplifier.

1.4 Quick reference data

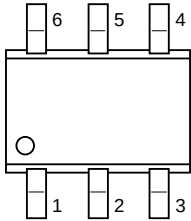
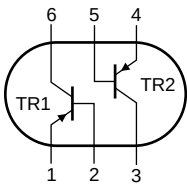
Table 1: Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage		-	-	-45	V
I_C	collector current		-	-	-100	mA
h_{FE}	DC current gain		200	290	450	
Δh_{FE}	h_{FE} matching		-	-	10	%
ΔV_{BE}	V_{BE} matching		-	-	2	mV

PHILIPS

2. Pinning information

Table 2: Discrete pinning

Pin	Description	Simplified outline	Symbol
1	emitter TR1	 SOT363	 sym018
2	base TR1		
3	collector TR2		
4	emitter TR2		
5	base TR2		
6	collector TR1		

3. Ordering information

Table 3: Ordering information

Type number	Package		
	Name	Description	Version
BCM857BS	SC-88	plastic surface mounted package; 6 leads	SOT363

4. Marking

Table 4: Marking codes

Type number	Marking code [1]
BCM857BS	A9*

[1] * = p: made in Hong Kong.
* = t: made in Malaysia.
* = W: made in China.

5. Limiting values

Table 5: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
Per transistor					
V_{CBO}	collector-base voltage	open emitter	-	-50	V
V_{CEO}	collector-emitter voltage	open base	-	-45	V
V_{EBO}	emitter-base voltage	open collector	-	-5	V
I_C	collector current (DC)		-	-100	mA
I_{CM}	peak collector current		-	-200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$	-	200	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-65	+150	°C
Per device					
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[1] -	300	mW

[1] Device mounted on a FR4 printed-circuit board, single-sided copper, tin-plated and standard footprint.

6. Thermal characteristics

Table 6: Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per device						
$R_{th(j-a)}$	thermal resistance from junction to ambient		[1] -	-	416	K/W

[1] Device mounted on a FR4 printed-circuit board, single-sided copper, tin-plated and standard footprint.

7. Characteristics

Table 7: Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per transistor						
I_{CBO}	collector-base cut-off current	$V_{CB} = -30\text{ V}; I_E = 0\text{ A}$	-	-	-15	nA
		$V_{CB} = -30\text{ V}; I_E = 0\text{ A}; T_j = 150\text{ }^{\circ}\text{C}$	-	-	-5	mA
I_{EBO}	emitter-base cut-off current	$V_{EB} = -5\text{ V}; I_C = 0\text{ A}$	-	-	-100	nA
h_{FE}	DC current gain	$V_{CE} = -5\text{ V}; I_C = -10\text{ }\mu\text{A}$	-	250	-	
		$V_{CE} = -5\text{ V}; I_C = -2\text{ mA}$	200	290	450	
V_{CEsat}	collector-emitter saturation voltage	$I_C = -10\text{ mA}; I_B = -0.5\text{ mA}$	-	-90	-250	mV
		$I_C = -100\text{ mA}; I_B = -5\text{ mA}$	-	-200	-600	mV
V_{BEsat}	base-emitter saturation voltage	$I_C = -10\text{ mA}; I_B = -0.5\text{ mA}$	-	-700	-	mV
		$I_C = -100\text{ mA}; I_B = -5\text{ mA}$	-	-850	-	mV
V_{BE}	base-emitter voltage	$V_{CE} = -5\text{ V}; I_C = -2\text{ mA}$	-600	-650	-750	mV
		$V_{CE} = -5\text{ V}; I_C = -10\text{ mA}$	-	-	-820	mV
C_c	collector capacitance	$V_{CB} = -10\text{ V}; I_E = i_e = 0\text{ A}; f = 1\text{ MHz}$	-	-	2.2	pF
C_e	emitter capacitance	$V_{EB} = -0.5\text{ V}; I_C = i_c = 0\text{ A}; f = 1\text{ MHz}$	-	10	-	pF
f_T	transition frequency	$V_{CE} = -5\text{ V}; I_C = -10\text{ mA}; f = 100\text{ MHz}$	100	250	-	MHz
Per device						
Δh_{FE}	DC current gain matching	$V_{CE} = -5\text{ V}; I_C = -2\text{ mA}$	-	-	10	%
ΔV_{BE}	base-emitter voltage matching	$V_{CE} = -5\text{ V}; I_C = -2\text{ mA}$	-	-	2	mV

8. Package outline

Plastic surface mounted package; 6 leads

SOT363

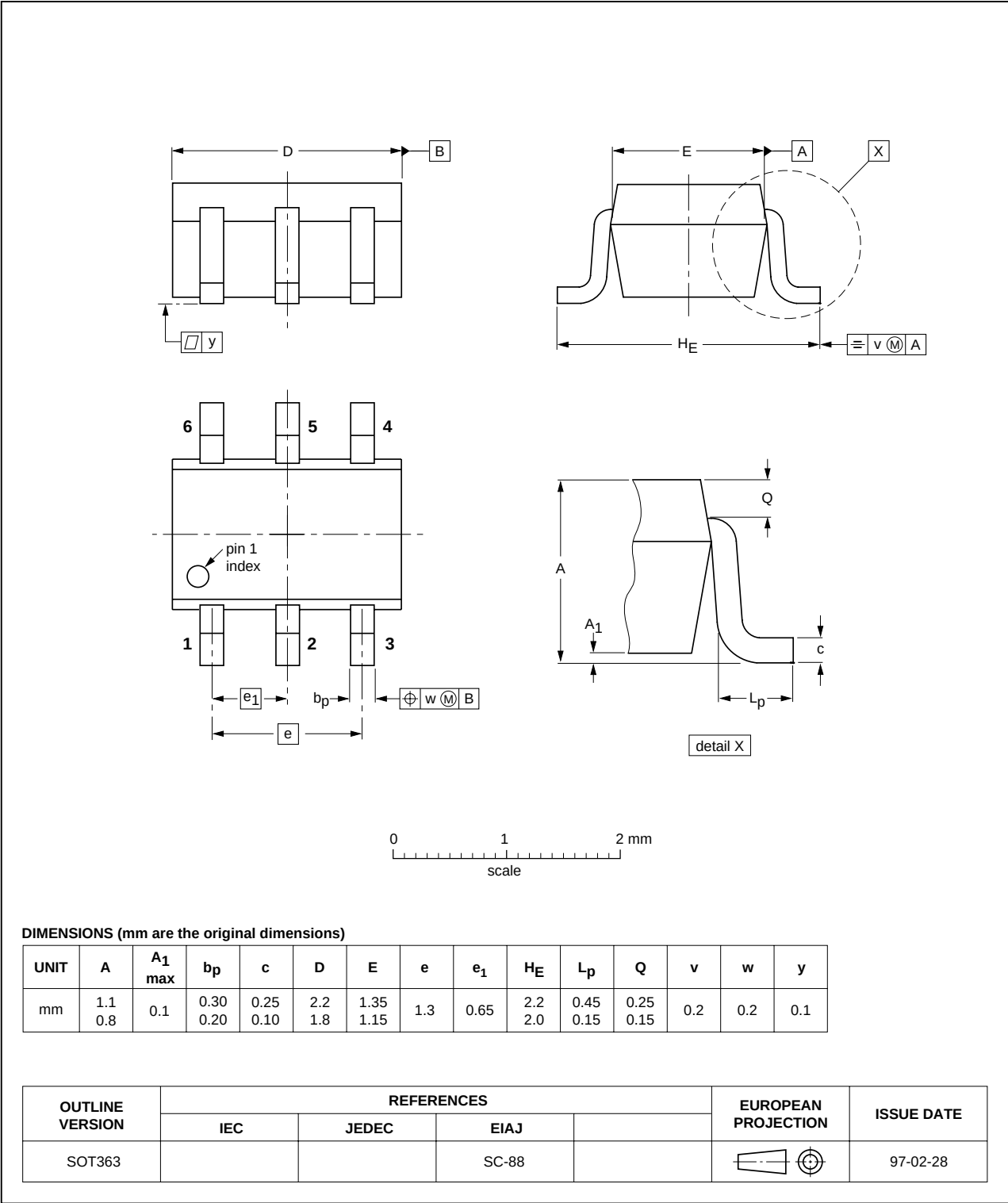


Fig 1. Package outline SOT363 (SC-88).



9. Packing information

Table 8: Packing methods
The indicated -xxx are the last three digits of the 12NC ordering code. [\[1\]](#)

Type number	Package	Description	Packing quantity	
			3000	10000
BCM857BS	SOT363	4 mm pitch, 8 mm tape and reel; T1	-115	-135

[1] For further information and the availability of packing methods, see [Section 14](#).

10. Revision history

Table 9: Revision history

Document ID	Release date	Data sheet status	Change notice	Order number	Supersedes
BCM857BS_1	20040914	Product data sheet	-	9397 750 13712	-

11. Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2] [3]}	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

12. Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

13. Disclaimers

Life support — These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

Right to make changes — Philips Semiconductors reserves the right to make changes in the products - including circuits, standard cells, and/or software - described or contained herein in order to improve design and/or performance. When the product is in full production (status 'Production'), relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN). Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no license or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.

14. Contact information

For additional information, please visit: <http://www.semiconductors.philips.com>

For sales office addresses, send an email to: sales.addresses@www.semiconductors.philips.com



15. Contents

1	Product profile	1
1.1	General description.	1
1.2	Features	1
1.3	Applications	1
1.4	Quick reference data.	1
2	Pinning information.	2
3	Ordering information.	2
4	Marking	2
5	Limiting values.	3
6	Thermal characteristics.	3
7	Characteristics.	4
8	Package outline	5
9	Packing information.	6
10	Revision history.	7
11	Data sheet status	8
12	Definitions	8
13	Disclaimers.	8
14	Contact information	8

